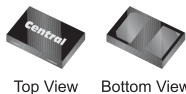
Material Composition Specification

SOD-882L Case



Top View Bottom View

Device average mass . . . . 0.75 mg
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.67%	0.02	Si	7440-21-3	2.67%	0.02	26,667
bond wire	gold	0.8%	0.006	Au	7440-57-5	0.8%	0.006	8,000
leadframe	copper	44.63%	0.335	Cu	7440-50-8	44.63%	0.3347	446,267
die attach	silver epoxy	2.73%	0.021	Ag	7440-22-4	1.93%	0.0145	19,333
				epoxy resin	Proprietary	0.8%	0.006	8,000
encapsulation*	EMC GREEN	47.41%	0.356	silica (fused)	60676-86-0	40.53%	0.304	405,333
				epoxy resin	29690-82-2	3.8%	0.0285	38,000
				phenol resin	9003-35-4	1.89%	0.0142	18,933
				carbon black	1333-86-4	0.24%	0.0018	2,400
				metal hydroxide	1309-42-8	0.95%	0.0071	9,467
plating	Ni/Pd/Au	1.76%	0.013	Ni	7440-02-0	1.69%	0.0127	16,933
				Pd	7440-05-3	0.05%	0.0004	533
				Au	7440-57-5	0.01%	0.0001	133
	matte tin	1.76%	0.013	Sn	7440-31-5	1.76%	0.013	17,600

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.